

General Description

The MAX8836Z high-frequency step-down converter is optimized to provide a fixed output voltage with ultralow dropout. The device integrates a high-efficiency PWM step-down converter for medium- and low-power transmission, and a $60m\Omega$ typical bypass FET for ultra low-dropout operation. A 200mA low-noise, high-PSRR low-dropout regulator (LDO) is also integrated.

Fast-switching allows the use of small ceramic input and output capacitors while maintaining low ripple voltage. The feedback network is integrated, further reducing external component count and total solution size. At high duty cycle, the MAX8836Z automatically switches to the bypass mode, connecting the input to the output through a low-impedance ($60m\Omega$ typ) MOSFET. The LDO in the MAX8836Z is designed for low-noise operation (35µV_{RMS} typ). Both the PWM step-down and LDO are individually enabled through separate logic-control interfaces.

The MAX8836Z is available in 16-bump, 2mm x 2mm WLP and UCSP™ packages (0.7mm max height).

Applications

WCDMA/NCDMA Cellular Handsets Wireless PDAs Smartphones

Ordering Information

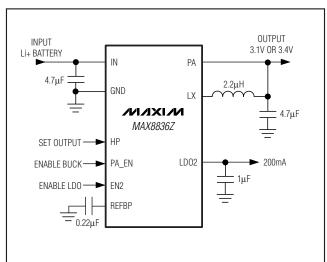
PART	PIN-PACKAGE	TEMP RANGE
MAX8836ZEWEEE+T	16 WLP (W162B2+1)	-40°C to +85°C
MAX8836ZEREEE+T	16 UCSP (R162A2+1)	-40°C to +85°C

⁺Denotes a lead-free/RoHS-compliant package.

Features

- **♦ PA Step-Down Converter**
 - Selectable Output Voltage (3.1V or 3.4V) 25µs Settling Time for 3.1V to 3.4Vout Change $60m\Omega$ PFET at 100% Duty-Cycle for Low Dropout
 - Low Output Voltage Ripple 1.2A Output Drive Capability ±2% Output Voltage Accuracy **Tiny External Components**
- **♦ Low-Noise LDO**
 - Low 35µVRMS (typ) Output Noise High 65dB (typ) PSRR **Guaranteed 200mA Output Current Drive** Capability ON/OFF Control
- ♦ Low 0.1µA Shutdown Current
- ♦ 2.7V to 5.5V Supply Voltage Range
- ♦ Thermal Shutdown
- ◆ Tiny 2mm x 2mm x 0.7mm WLP and UCSP Packages (4 x 4 Grid)

Typical Operating Circuit



Pin Configuration appears at end of data sheet.

UCSP is a trademark of Maxim Integrated Products, Inc.

T = Tape and reel.

ABSOLUTE MAXIMUM RATINGS

IN1A, IN1B, IN2, EN2, REFBP to AGND0.3V to +6.0V	PAA and PAB Short Circuit to GND or INContinuous
PAA, PAB, PA_EN, HP to AGND0.3V to (VIN1A/VIN1B + 0.3V)	Continuous Power Dissipation ($T_A = +70^{\circ}C$)
LDO2 to AGND0.3V to (V _{IN2} + 0.3V)	16-Bump WLP (derate 12.5mW/°C above +70°C)1W
IN2 to IN1B/IN1A0.3V to +0.3V	16-Bump UCSP (derate 12.5mW/°C above +70°C)1W
PGND to AGND0.3V to +0.3V	Junction Temperature+150°C
LX Current0.7A _{RMS}	Storage Temperature Range65°C to +150°C
IN1A/IN1B and PAA/PAB Current2ARMS	Bump Temperature (soldering, reflow)+260°C

Note: This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry-standard specification, JEDEC 020A, paragraph 7.6, Table 3 for IR/VPR and Convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN1A} = V_{IN1B} = V_{IN2} = V_{PA_EN} = V_{EN2} = 3.6V$, $V_{HP} = 0V$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$. Typical values are at $T_A = +25^{\circ}C$, unless otherwise noted.) (Note 1)

PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS	
INPUT SUPPLY				•			•	
Input Voltage	VIN1A, VIN1B, VIN2			2.7		5.5	V	
Input Undervoltage Threshold	V _{IN1A} , V _{IN1B} , V _{IN2} rising, 1	80mV ty	pical hysteresis	2.52	2.63	2.70	V	
HP, PA_EN, EN2 Pulldown Resistor				400	800	1600	kΩ	
Object of the control	V		T _A = +25°C		0.1	4		
Shutdown Supply Current	VPA_EN = VEN2 = 0V		T _A = +85°C		0.1		μΑ	
	$V_{PA_EN} = 0V$, $I_{LDO2} = 0A$				100	150		
No-Load Supply Current	$V_{EN2} = 0V$, $I_{PA} = 0A$, switching			3500		μΑ		
	V _{EN2} = 0V, I _{PA} = 0A, no sw	OV, IPA = 0A, no switching			180			
THERMAL PROTECTION								
Thermal Shutdown	T _A rising, 20°C typical hysteresis				+160		°C	
LOGIC CONTROL								
PA_EN, EN2, HP Logic-Input High Voltage				1.3			V	
PA_EN, EN2, HP Logic-Input Low Voltage						0.4	V	
Logic-Input Current	V 0V		T _A = +25°C		0.01	1		
(PA_EN, EN2, HP)	V _{IL} = 0V		T _A = +85°C		0.1		μA	
PA OUTPUT VOLTAGE								
	I _L X = 0A, V _{IN1A} = V _{IN1B}	HP =	0	3.365	3.434	3.503	V	
Output Voltage	$= V_{IN2} = 3.9V$	HP =	1	3.010	3.065	3.190		
Output Voltage Load Regulation					I _{LX} x R _L /2		V	

ELECTRICAL CHARACTERISTICS (continued)

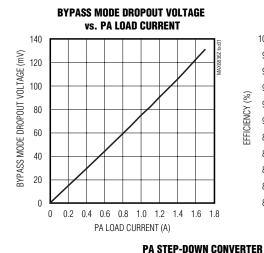
 $(V_{IN1A} = V_{IN1B} = V_{IN2} = V_{PA_EN} = V_{EN2} = 3.6V$, $V_{HP} = 0V$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$. Typical values are at $T_A = +25^{\circ}C$, unless otherwise noted.) (Note 1)

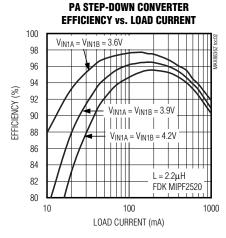
PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
LX						
On-Resistance	p-channel MOSFET switch, I _{LX} = -40mA			0.15		Ω
On-Resistance	n-channel MOSFET rectifier, IL	n-channel MOSFET rectifier, I _{LX} = 40mA				22
LVI sakaga Current	V _{IN1A} = V _{IN1B} = V _{IN2} = 5.5V,	T _A = +25°C		0.1	5	^
LX Leakage Current	$V_{LX} = 0V$	T _A = +85°C		1		μΑ
p-Channel MOSFET Peak Current Limit	V _L X = 0V	$V_{LX} = 0V$				А
n-Channel MOSFET Valley Current Limit			1.1	1.3	1.6	А
Minimum On- and Off-Times				0.07		μs
Power-Up Delay	From PA_EN rising to LX rising	9		80	190	μs
BYPASS			•			
On Desistance	p-channel MOSFET bypass,	T _A = +25°C		0.060	0.1	
On-Resistance	$I_{PA} = -90 \text{mA}$	T _A = +85°C		0.1		Ω
Bypass Current Limit	VPA = 0V	<u>.</u>	0.8	1.4	1.8	А
Total Bypass Current Limit	$V_{LX} = V_{PA} = 0V$	2.1	2.9	3.6	А	
Bypass Threshold	V _{IN2} rising, 150mV hysteresis		0.985 x V _{PA}		V/V	
5 0%1 1 0	VIN1A = VIN1B = VIN2 = 5.5V.	T _A = +25°C		0.01	5	
Bypass Off-Leakage Current	$V_{PAA} = V_{PAB} = 0V$ $T_{A} = +85^{\circ}C$			0.1		μΑ
LDO2		•	•			
Output Voltage V _{LDO2}	V _{IN2} = 5.5V, I _{LDO2} = 1mA; V _{IN2} = 3.4V, I _{LDO2} = 1mA		2.765	2.85	2.936	V
Output Current			200			mA
Current Limit	$V_{LDO2} = 0V$	VI DO2 = 0V		550	750	mA
Dropout Voltage	I _{LDO2} = 100mA, T _A = +25°C (V _{LDO2} ≥ 2.5V)		70		mV
Line Regulation	V _{IN2} stepped from 3.5V to 5.5V, I _{LDO2} = 100mA			2.4		mV
Load Regulation	I _{LDO2} stepped from 50µA to 2	00mA		25		mV
Power-Supply Rejection ΔV _{LDO2} /ΔV _{IN2}	10Hz to 10kHz, C _{LDO2} = 1µF, I _{LDO2} = 30mA			65		dB
Output Noise	100Hz to 100kHz, C _{LDO2} = 1µF, I _{LDO2} = 30mA			35		μV _{RMS}
Output Capacitor for Stable	0 < I _{LDO2} < 10mA			100		nF
Operation	0 < I _{LDO2} < 200mA		1		μF	
Shutdown Output Impedance	V _{EN2} = 0V			1		kΩ
REFBP	•					•
REFBP Output Voltage	0 ≤ I _{REFBP} ≤ 1µA		1.237	1.250	1.263	V
REFBP Supply Rejection	V _{IN2} stepped from 2.55V to 5.5V			0.2	5	mV

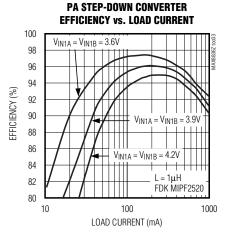
Note 1: All devices are 100% production tested at $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design.

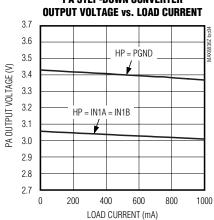
Typical Operating Characteristics

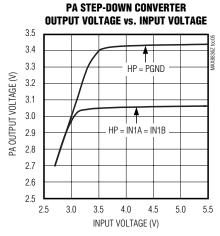
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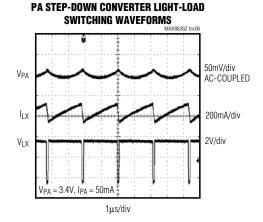


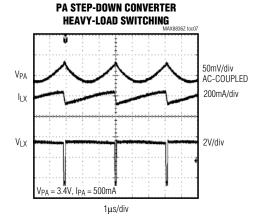






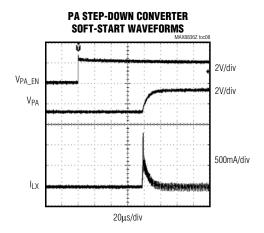


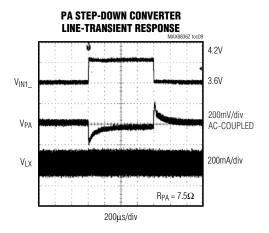


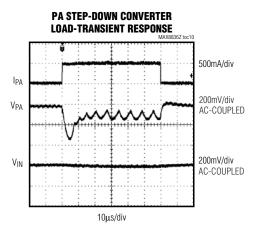


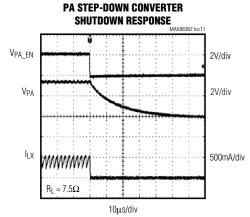
Typical Operating Characteristics (continued)

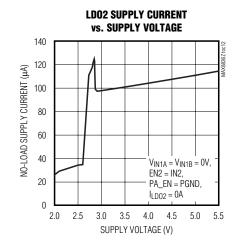
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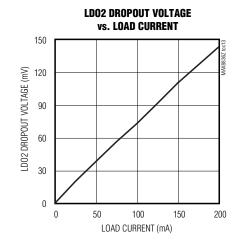






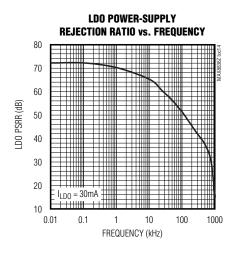


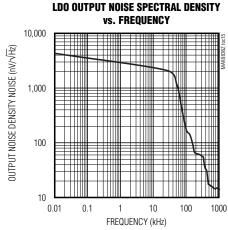


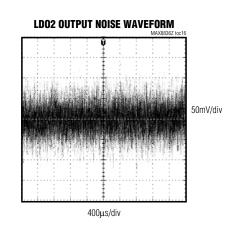


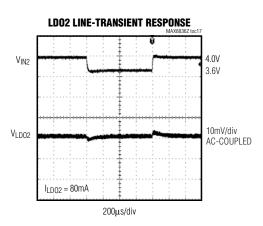
_Typical Operating Characteristics (continued)

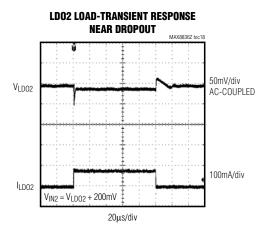
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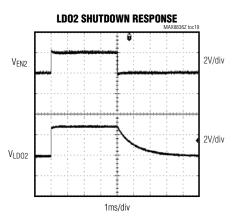












Pin Description

PIN	NAME	FUNCTION
A1	REFBP	Reference Noise Bypass. Bypass REFBP to AGND with a 0.22μF ceramic capacitor to reduce noise on the LDO outputs. REFBP is internally pulled down through a 1kΩ resistor during shutdown.
A2	AGND	Low-Noise Analog Ground. Connect AGND to PGND using a common ground plane. Refer to the MAX8805W Evaluation Kit for more information.
А3	N.I.C.	Not Internally Connected. Connect to AGND for improved thermal performance.
A4	PGND	Power Ground for PA Step-Down Converter. Connect AGND to PGND using a common ground plane. Refer to the MAX8805W Evaluation Kit for more information.
B1	LDO2	200mA LDO Regulator 2 Output. Bypass LDO2 with a 1μF ceramic capacitor as close as possible to LDO2 and AGND. LDO2 is internally pulled down through a 1kΩ resistor when this regulator is disabled.
B2	PA_EN	PA Step-Down Converter Enable. Active-high enable input. Connect to IN1A/IN1B or logic-high for normal operation. Pulled down to ground through an internal $800k\Omega$ resistor.
В3	EN2	LDO2 Enable. Active-high enable input. Connect to IN2 or logic-high for normal operation. Pulled down to ground through an internal $800 \mathrm{k}\Omega$ resistor.
B4	LX	Inductor Connection. Connect an inductor from LX to the output of the PA step-down converter.
C1	IN2	Supply Voltage Input for LDO2 and Internal Reference. Connect IN2 to a battery or supply voltage from 2.7V to 5.5V. Bypass IN2 with a 2.2µF ceramic capacitor as close as possible to IN2 and AGND. Connect IN2 to the same source as IN1A and IN1B.
C2	HP	PA Output Voltage Select. Pulled down to ground through an internal $800 k\Omega$ resistor.
C3, C4	IN1B, IN1A	Supply Voltage Input for PA Step-Down Converter. Connect IN1_ to a battery or supply voltage from 2.7V to 5.5V. Bypass the connection of IN1_ with a 4.7µF ceramic capacitor as close as possible to IN1_ and PGND. IN1A and IN1B are internally connected together. Connect IN1_ to the same source as IN2.
D1	N.C.	Internally Connected to IN2. Do not connect to this pin.
D2	T.P.	Test Point. This pin is used internally for factory test. This pin must be either externally connected to AGND or unconnected. This pin has an internal 120 k Ω pulldown to AGND.
D3, D4	PAB, PAA	PA Connection for Bypass Mode. Internally connected to IN1_ using the internal bypass MOSFET during bypass mode. PA_ is connected to the internal feedback network. Bypass PA_ with a 4.7µF ceramic capacitor as close as possible to PA_ and PGND.

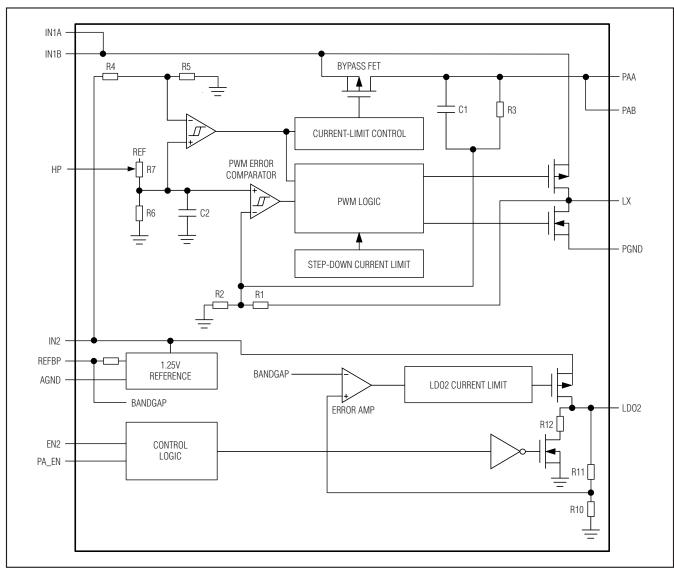


Figure 1. Block Diagram

Detailed Description

The MAX8836Z is designed to provide a fixed output voltage of 3.4V with ultra-low dropout. The device contains a high-frequency, high-efficiency step-down converter, and 200mA low-noise LDO. The step-down converter delivers over 1.2A. The hysteretic PWM control scheme provides extremely fast transient response. A $60m\Omega$ bypass FET connects directly to the battery during high-power transmission.

Step-Down Converter Control Scheme

A hysteretic PWM control scheme ensures high efficiency, fast switching, fast transient response, low-output ripple, and physically tiny external components. The control scheme is simple: when the output voltage is below the regulation threshold, the error comparator begins a switching cycle by turning on the high-side switch. This high-side switch remains on until the minimum on-time expires and the output voltage is within regulation, or the inductor current is above the currentlimit threshold. Once off, the high-side switch remains off until the minimum off-time expires and the output voltage falls again below the regulation threshold. During the off period, the low-side synchronous rectifier turns on and remains on until the high-side switch turns on again. The internal synchronous rectifier eliminates the need for an external Schottky diode.

Voltage-Positioning Load Regulation

The MAX8836Z step-down converter utilizes a unique feedback network. By taking DC feedback from the LX node through R1 in Figure 1, the usual phase lag due to the output capacitor is removed, making the loop exceedingly stable and allowing the use of very small ceramic output capacitors. To improve the load regulation, resistor R3 is included in the feedback. This configuration yields load regulation equal to half of the inductor's series resistance multiplied by the load current. This voltage-positioning load regulation greatly reduces overshoot during load transients or when changing the output voltage from one level to another.

Step-Down Converter Bypass Mode

During high-power transmission, the bypass mode connects IN1A and IN1B directly to PAA and PAB with the internal $60m\Omega$ (typ) bypass FET, while the step-down converter is forced into 100% duty-cycle operation. The low on-resistance in this mode provides low dropout, long battery life, and high output current capability.

Automatic Bypass Mode

Forced bypass mode is automatically invoked when the DC-DC converter operates at more than 99% duty cycle (typ). See Figure 2. Note that IN2 is used instead of IN1 to prevent switching noise from causing false engagement of automatic bypass mode. For this reason, IN2 must be connected to the same source as IN1.

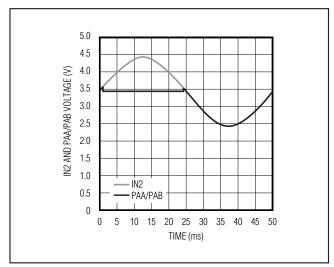


Figure 2. V_{IN2} and V_{PA} with Automatic Entry/Exit into Bypass Mode

Shutdown Mode

Connect PA_EN to GND or logic-low to place the MAX8836Z PA step-down converter in shutdown mode. In shutdown, the control circuitry, internal switching MOSFET, and synchronous rectifier turn off and LX becomes high impedance. Connect PA_EN to IN1_ or logic-high for normal operation.

Connect EN2 to GND or logic-low to place LDO2 in shutdown mode. In shutdown, the output of the LDO is pulled to ground through an internal $1k\Omega$ resistor.

When the PA step-down and LDO are in shutdown, the MAX8836Z enters a very low power state, where the input current drops to $0.1\mu A$ (typ).

Step-Down Converter Soft-Start

The MAX8836Z PA step-down converter has internal soft-start circuitry that limits inrush current at startup, reducing transients on the input source. Soft-start is particularly useful for supplies with high output impedance such as Li+ and alkaline cells. See the PA Step-Down Converter Soft-Start Waveforms in the *Typical Operating Characteristics*.

Thermal Shutdown

Thermal shutdown limits total power dissipation in the MAX8836Z. If the junction temperature exceeds +160°C, thermal-shutdown circuitry turns off the IC, allowing it to cool. The IC turns on and begins soft-start after the junction temperature cools by 20°C. This results in a pulsed output during continuous thermal-overload conditions.

Applications Information

Output Voltages

The MAX8836Z provides a fixed output voltage of 3.4V (HP = 0), or BYPASS mode if duty cycle is higher than 99% (typ).

If HP = 1, the MAX8836Z provides a 3.1V fixed output voltage.

The LDO2 output voltage is factory preset to 2.85V.

LDO Dropout Voltage

The regulator's minimum input/output differential (or dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the MAX8836Z LDO uses a p-channel MOSFET pass transistor, the dropout voltage is a function of drain-to-source on-resistance (RDS(ON)) multiplied by the load current (see the *Typical Operating Characteristics*).

Inductor Selection

The MAX8836Z operates with a switching frequency of 1.6MHz and utilizes a 2.2µH inductor. The switching frequency of the MAX8836Z results in great efficiency with a physically small inductor. See the *Typical Operating Characteristics* for efficiency graphs.

The inductor's DC current rating only needs to match the maximum load of the application because the MAX8836Z features zero current overshoot during startup and load transients. For optimum transient response and high efficiency, choose an inductor with DC series resistance in the $50\text{m}\Omega$ to $150\text{m}\Omega$ range. See Table 1 for suggested inductors and manufacturers.

Output Capacitor Selection

For the PA step-down converter, the output capacitor (CPA) is required to keep the output voltage ripple small and ensure regulation loop stability. CPA must have low impedance at the switching frequency. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. Due to the unique feedback network, the output capacitance can be very low. A 4.7µF capacitor is recommended for most applications. For optimum load-transient performance and very low output ripple, the output capacitor value can be increased.

For LDO2, the minimum output capacitance required is dependent on the load currents. For loads less than 10mA, it is sufficient to use a $0.1\mu F$ capacitor for stable operation over the full temperature range. With rated maximum load currents, a minimum of $1\mu F$ is recommended. Reduce output noise and improve load-transient response, stability, and power-supply rejection by using larger output capacitors.

Note that some ceramic dielectrics exhibit large capacitance and ESR variation with temperature. With dielectrics such as Z5U and Y5V, it is necessary to use 2.2 μ F or larger to ensure stability at temperatures below -10°C. With X7R or X5R dielectrics, 1μ F is sufficient at all operating temperatures. These regulators are optimized for ceramic capacitors. Tantalum capacitors are not recommended.

Input Capacitor Selection

The input capacitor (C_{IN1}) of the PA converter reduces the current peaks drawn from the battery or input power source and reduces switching noise in the MAX8836Z. The impedance of C_{IN1} at the switching frequency should be kept very low. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. A $4.7\mu F$ capacitor is recommended for most applications. For optimum noise immunity and low input ripple, the input capacitor value can be increased.

Table 1. Suggested Inductors

MANUFACTURER	SERIES	INDUCTANCE (µH)	ESR (Ω)	CURRENT RATING (mA)	DIMENSIONS (mm)
Coilcraft	LPO3310	1.0 1.5 2.2	0.07 0.10 0.13	1600 1400 1100	$3.3 \times 3.3 \times 1.0 = 11 \text{mm}^3$
	MIPF2520	1.0 1.5 2.2	0.05 0.07 0.08	1500 1500 1300	2.5 x 2.0 x 1.0 = 5mm ³
FDK	MIPS2520	1.3 2.0	0.09 0.11	1500 1200	$2.5 \times 2.0 \times 1.0 = 5 \text{mm}^3$
	MIPF2016	1.0 2.2	0.11	1100	$2.0 \times 1.6 \times 1.0 = 3.2 \text{mm}^3$
Murata	LQH32C_53	1.0 2.2	0.06 0.10	1000 790	3.2 x 2.5 x 1.7 = 14mm ³
Sumida	CDRH2D09	1.2 1.5 2.2	0.08 0.09 0.12	590 520 440	$3.0 \times 3.0 \times 1.0 = 9 \text{mm}^3$
Taiyo Yuden	CDRH2D11	1.5 2.2 3.3	0.05 0.08 0.10	680 580 450	3.2 x 3.2 x 1.2 = 12mm ³
	CB2518T	2.2 4.7	0.09 0.13	510 340	$2.5 \times 1.8 \times 2.0 = 9 \text{mm}^3$
	D3010FB	1.0	0.20	1170	$3.0 \times 3.0 \times 1.0 = 9 \text{mm}^3$
токо	D2812C	1.2 2.2	0.09 0.15	860 640	$3.0 \times 3.0 \times 1.2 = 11 \text{mm}^3$
	D310F	1.5 2.2	0.13 0.17	1230 1080	$3.6 \times 3.6 \times 1.0 = 13 \text{mm}^3$
	D312C	1.5 2.2	0.10 0.12	1290 1140	3.6 x 3.6 x 1.2 = 16mm ³

For the LDO, use an input capacitance equal to the value of the output capacitance of LDO2. Larger input capacitor values and lower ESR provide better noise rejection and line-transient response.

Note that some ceramic dielectrics exhibit large capacitance and ESR variation with temperature. With dielectrics such as Z5U and Y5V, it may be necessary to use two times the output capacitor value of LDO2 (or larger) to ensure stability at temperatures below -10°C. With X7R or X5R dielectrics, a capacitance equal to the output capacitor value is sufficient at all operating temperatures.

Thermal Considerations

In most applications, the MAX8836Z does not dissipate much heat due to the high efficiency. However, in applications where the MAX8836Z operates at high ambient temperature with heavy loads, the heat dissipated may exceed the maximum junction temperature of the IC. If the junction temperature reaches approximately +160°C, all power switches are turned off and LX and PA_ become high impedance, and LDO2 is pulled down to ground through an internal $1\mathrm{k}\Omega$ pull-down resistor.

The MAX8836Z maximum power dissipation depends on the thermal resistance of the IC package and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The power dissipated in the device is:

PDISS = PPA x (1/ η PA - 1) + ILDO2 x (VIN2 - VLDO2) where η PA is the efficiency of the PA step-down converter and PPA is the output power of the PA step-down converter.

The maximum allowed power dissipation is:

$$PMAX = (TJMAX - TA)/\theta JA$$

where (T_{JMAX} - T_A) is the temperature difference between the MAX8836Z die junction and the surrounding air; θ_{JA} is the thermal resistance of the junction through the PCB, copper traces, and other materials to the surrounding air.

PCB Layout

High switching frequencies and relatively large peak currents make the PCB layout a very important part of design. Good design minimizes excessive EMI on the feedback paths and voltage gradients in the ground plane, resulting in a stable and well-regulated output. Connect C_{IN1} close to IN1A/IN1B and PGND. Connect the inductor and output capacitor as close as possible to the IC and keep their traces short, direct, and wide. Keep noisy traces, such as the LX node, as short as possible. Figure 3 illustrates an example PCB layout and routing scheme. Note that Figure 3 does not show the common ground plane connection of AGND and PGND. Refer to the MAX8805W Evaluation Kit for more information.

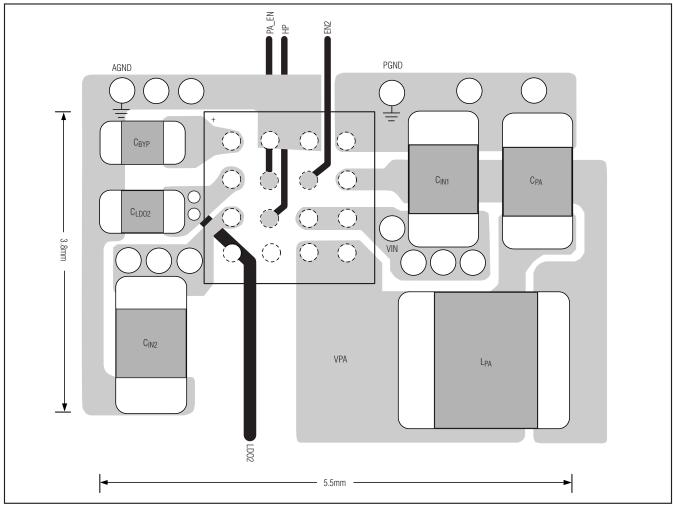


Figure 3. Recommended PCB Layout

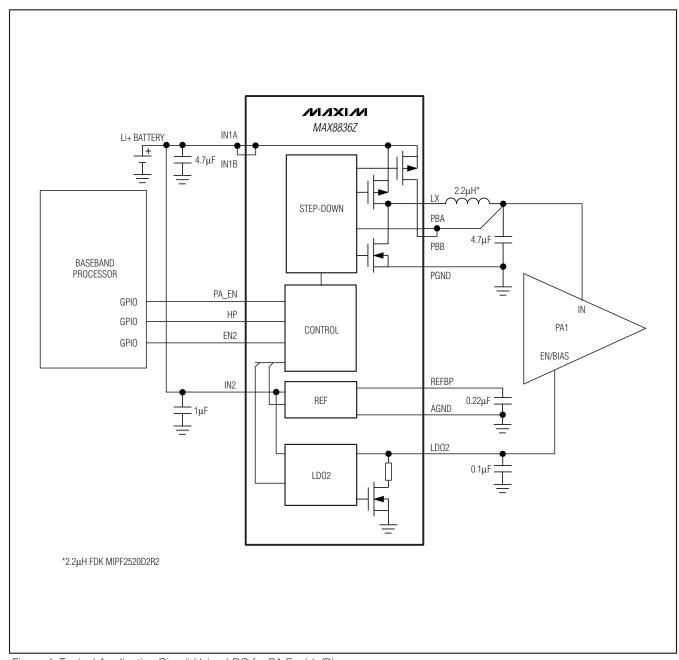


Figure 4. Typical Application Circuit Using LDO for PA Enable/Bias

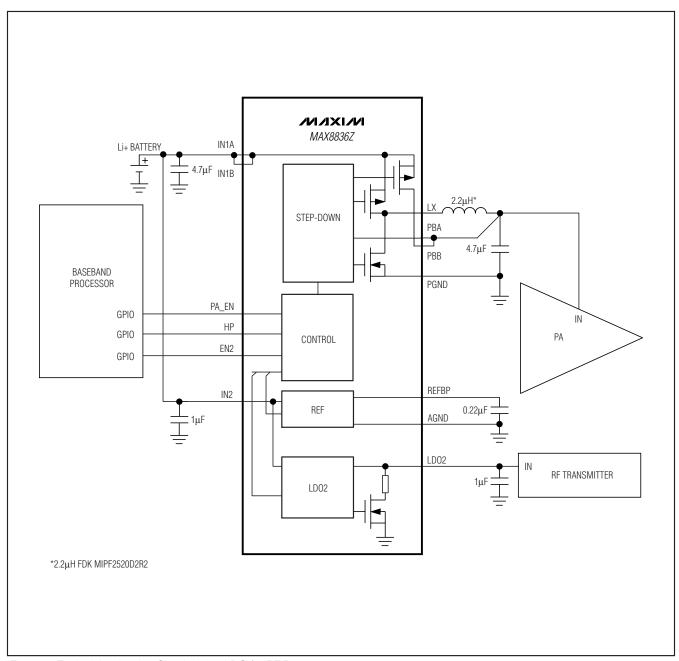


Figure 5. Typical Application Circuit Using LDO for RF Power

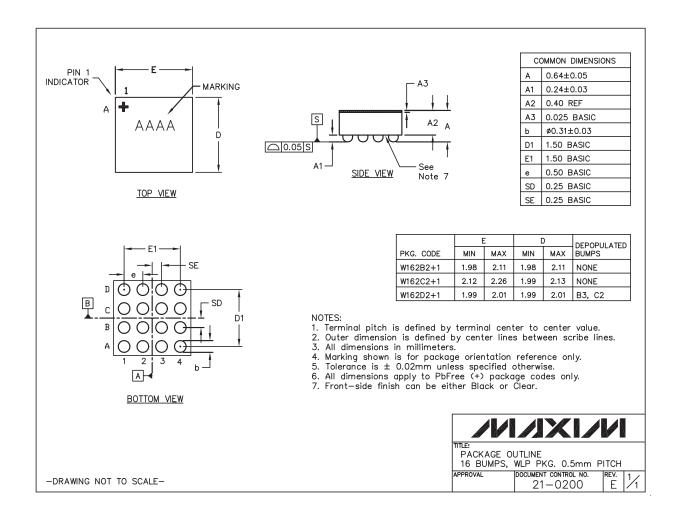
_____Chip Information

PROCESS: BiCMOS

Package Information

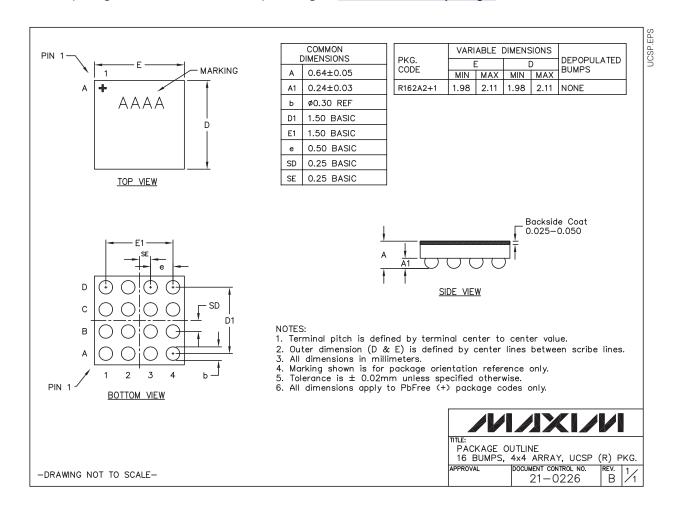
For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
16 UCSP	R162A2+1	<u>21-0226</u>
16 WLP	W162B2+1	<u>21-0200</u>



Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.



Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	3/08	Initial release	_
1	9/08	Added UCSP package option	1, 2, 16

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